



Product / Process Change Notice

No.: Z200-PCN-DM201912-06-A

Date: December 30, 2019

Change Title : W74M64JV 3.3V Authentication Flash to replace W74M64FV 3.3V Authentication Flash Memories

Change Classification: Major Minor with customer notification Minor without customer notification
Change item : Design Raw Material Wafer FAB Assembly Testing Packing Others

Affected Product(s) :

W74M64FVSSIQ

Description of Change(s)

W74M64JV 3.3V Authentication Flash Memories is using Winbond 58nm Flash technology, It is function-compatible with W74M64FV 3.3V Authentication devices and offering improved performance, features and availability.

1. Individual Block/Sector array protection.
2. Special OTP protection. (Please refer the W74M64JV Authentication datasheet)

Reason for Change(s) :

1. W74M64FV Authentication EOL. (Please refer to attachment IV for details)
2. New generation features improvement and Command backward compatible. (Please refer to attachment I comparison table)

Impact of Change(s) : (positive & negative)

Form : No Change
 Fit : No Change
 Function : No Concern (Please refer to attachment I)
 Reliability : No Concern (Please refer to attachment II)
 Hazardous Substances: No Concern (Please refer to attachment III)

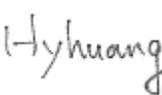
Qualification Plan/ Results :

Based on Winbond W74M Reliability report, the new product meets our criteria and no quality concern (refer to Attachment II in details)

Implementation Plan :

Please refer to attachment IV for details.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: Please refer to attachment IV.

Originator: (QA)		Approval: (QA Dept. Manager)		Approval: (QRA Director)	
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Winbond Electronics Corporation

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Product Obsolescence Notice

W74M64FV 3.3V Authentication Memories

Notification Date: January 03, 2020

Dear Valued Customer,

This letter is to notify you of Winbond's intention to terminate production of the W74M64FV 3.3V Authentication memory, and replace it with the W74M64JV 3.3V Authentication Flash. Replacement part number is listed below:

Winbond Current PN (58nm F-Series)	Winbond Primary Replacement PN (58nm J-Series)
W74M64FVSSIQ	W74M64JVSSIQ

The W74M64JV 3.3V Authentication device features:

Features

- a) Command backward compatible with W74M64JV 3.3V Authentication Flash
- b) Clock operation up to 104MHz, SPI with Single / Dual / Quad / QPI
- c) Individual Block/Sector array protection

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W74M64FV	Jan./03/2020	Jul./03/2020	Jan./03/2021	W74M64JV	Sep./2020	Oct./30/2019

Jooweon (JW) Park
Technology Executive of Flash Marketing